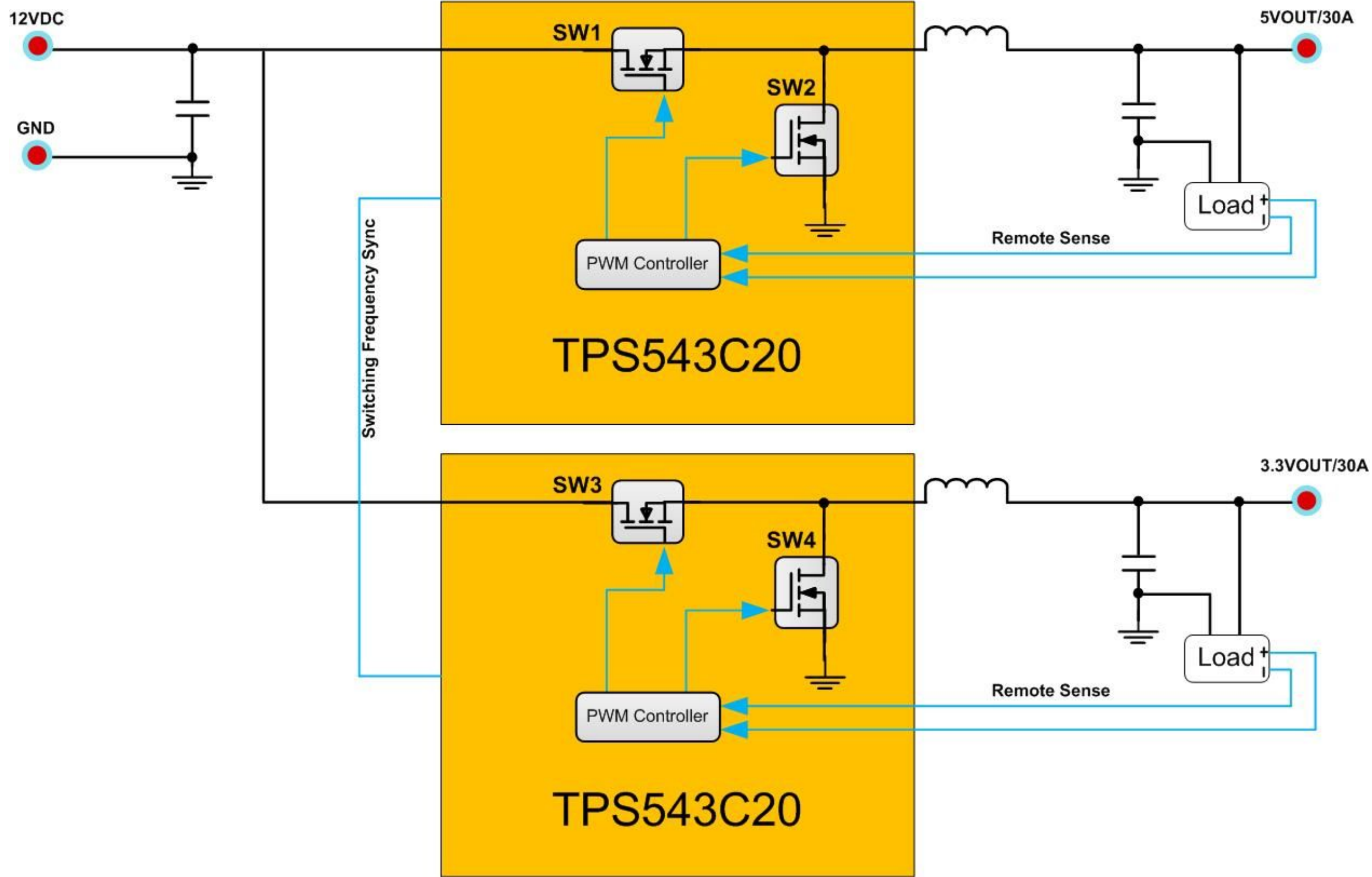


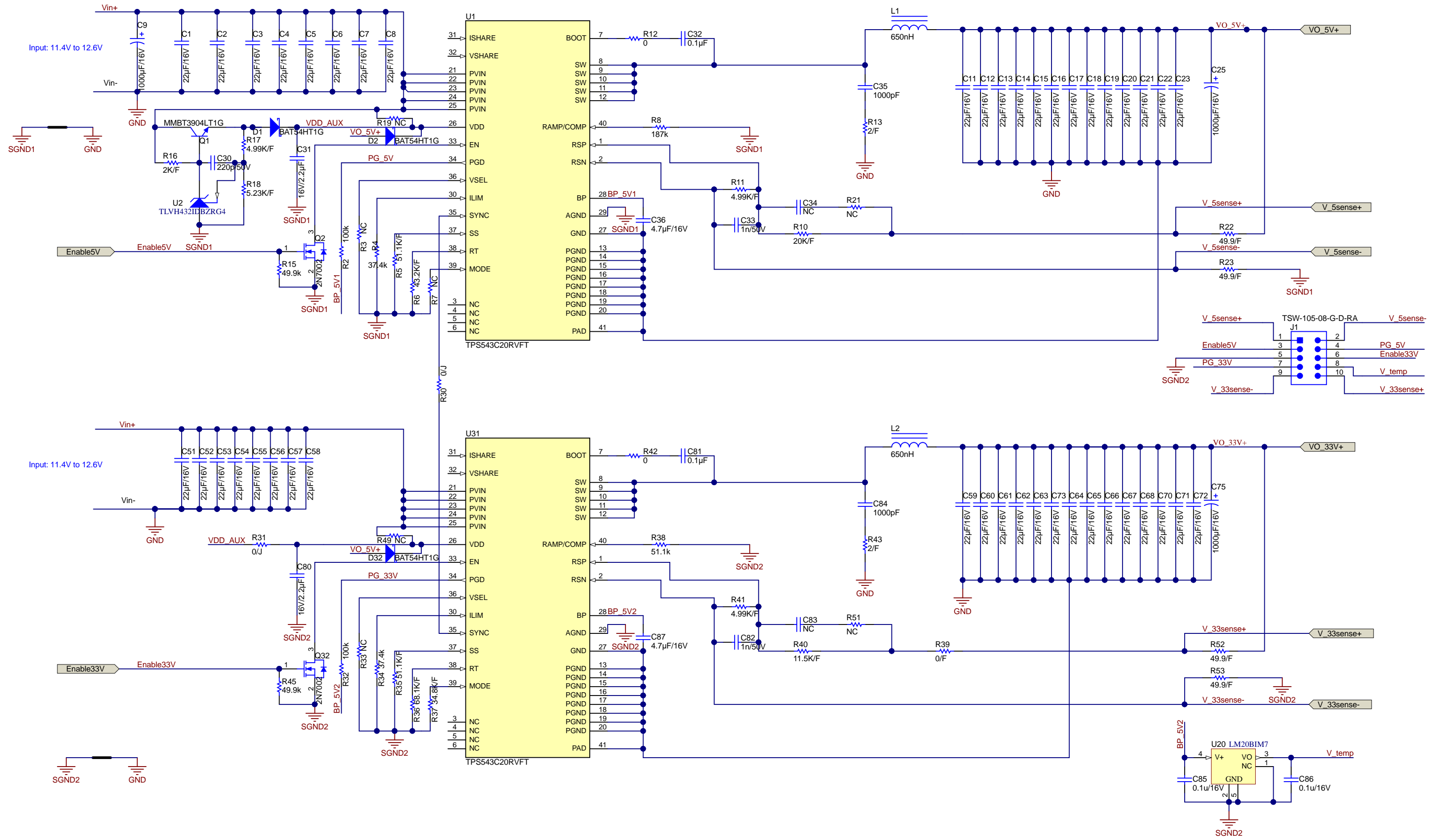
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable:	Designed for: Public Release	Mod. Date: 6/28/2017
TID #: 01444	Project Title: 180W Dual Buck Converter	
Number: TIDA-01444	Rev: E1	Sheet Title: 180W Dual Buck Converter
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: CoverSheet.SchDoc	Size: B
Engineer: Cheng Liu	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	





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Orderable:	Designed for: Public Release	Mod. Date: 6/20/2017
TID #: 01444	Project Title: 180W Dual Buck Converter	
Number: TIDA-01444	Rev: E1	Sheet Title:
SVN Rev: Version control disabled		Assembly Variant: 001
Drawn By:	File: BlankSheet_SchDoc	Sheet: 2 of 3
Engineer: Cheng Liu	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	Size: B



H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

H9 SJ-5303 (CLEAR) H10 SJ-5303 (CLEAR) H11 SJ-5303 (CLEAR) H12 SJ-5303 (CLEAR)

DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA-01444  
PCB Rev: E1

PCB LOGO  
Texas Instruments

PCB LOGO  
Pb-Free Symbol

PCB LOGO  
FCC disclaimer

Variant/Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1  
PCB Label  
Size: 0.65" x 0.20"

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable:	Designed for: Public Release	Mod. Date: 6/28/2017
TID #: 01444	Project Title: 180W Dual Buck Converter	
Number: TIDA-01444	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: EVM_Hardware.SchDoc	Size: B
Engineer: Cheng Liu	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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